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**AMENDMENTS TO THE CLAIMS:**

This listing of claims will replace all prior versions, and listings, of claims in the application (please note, Applicants have assumed that the previous listing of claims in the Amendment filed on October 14, 2003 has been entered):

**LISTING OF CLAIMS:**

Claim 1 (previously presented): A method of wiring formation comprising the steps of:

- forming a feeder film partially on a substrate;
- forming on the substrate a plating base film such that the plating base film partially overlaps the feeder film;
- forming a plated wiring on the plating base film; and
- selectively removing at least a portion of the feeder film that is exposed from the plated wiring.

Claim 2 (original): A method of wiring formation according to Claim 1, wherein the step of forming on the substrate a plating base film is performed using a physical film making process.

Claim 3 (original): A method of wiring formation according to Claim 1, wherein the step of forming a plated wiring on the plating base film is performed using an electrolytic plating process.

Claim 4 (original): A method of wiring formation according to Claim 1, wherein the step of selectively removing at least a portion of the feeder film that is exposed from the plated wiring is performed using a wet etching process.

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**Claim 5 (original):** A method of wiring formation according to Claim 1, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.

**Claim 6 (original):** A method of wiring formation according to Claim 1, wherein the plating base film comprises at least one of an adhesive layer and a diffusion preventive layer.

**Claim 7 (previously presented):** A method of wiring formation comprising the steps of:

- forming a feeder film partially on a substrate;
- forming on the substrate a resist pattern which has an opening defining a wiring forming area, such that a portion of the feeder film is exposed from the opening in the resist pattern;
- forming a plating base film at least on the substrate in the opening;
- forming a plated wiring on the plating base film in the opening;
- removing the resist pattern; and
- selectively removing at least a portion of the feeder film that is exposed from the plated wiring.

**Claim 8 (original):** A method of wiring formation according to Claim 7, wherein the step of forming on the substrate a plating base film is performed using a physical film making process.

**Claim 9 (original):** A method of wiring formation according to Claim 7, wherein the step of forming a plated wiring on the plating base film is performed using an electrolytic plating process.

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**Claim 10 (original):** A method of wiring formation according to Claim 7, wherein the step of selectively removing at least a portion of the feeder film that is exposed from the plated wiring is performed using a wet etching process.

**Claim 11 (original):** A method of wiring formation according to Claim 7, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.

**Claim 12 (original):** A method of wiring formation according to Claim 7, wherein the plating base film comprises at least one of an adhesive layer and a diffusion preventive layer.

**Claim 13 (previously presented):** A method of manufacturing an electronic component comprising the steps of:

- providing a substrate;
- forming a feeder film partially on the substrate;
- forming on the substrate a plating base film by using a physical film making process such that the plating base film partially overlaps the feeder film;
- forming a plated wiring on the plating base film using an electrolytic plating process; and
- selectively removing at least a portion of the feeder film that is exposed from the plated wiring, using a wet etching process; wherein
- the plating base film includes a diffusion preventive layer.

**Claim 14 (original):** A method according to Claim 13, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.

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Claim 15 (previously presented): A method according to Claim 16, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.

Claim 16 (original): A method according to Claim 13, wherein the plating base film comprises at least one of an adhesive layer and a diffusion preventive layer.

Claim 17 (previously presented): A method of manufacturing an electronic component comprising the steps of:

providing a substrate;

forming a feeder film partially on a substrate;

forming on the substrate a resist pattern which has an opening defining a wiring forming area, such that a portion of the feeder film is exposed from the opening in the resist pattern;

forming a plating base film at least on the substrate in the opening using a physical film making process;

forming a plated wiring on the plating base film in the opening using an electrolytic plating process;

removing the resist pattern; and

selectively removing at least a portion of the feeder film that is exposed from the plated wiring, using a wet etching; wherein

the plating base film includes a diffusion preventive layer.

Claim 18 (original): A method according to Claim 17, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.

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Claim 19 (previously presented): A method according to Claim 20, wherein a width of a portion of the plating base film that is stacked on the feeder film is wider than the smallest wire width of the feeder film.

Claim 20 (original): A method according to Claim 17, wherein the plating base film comprises at least one of an adhesive layer and a diffusion preventive layer.

Claim 21-24 (canceled).

Claim 25 (previously presented): A method according to Claim 1, further comprising a step of forming on the substrate a resist pattern having a reversed [taped] shape.

Claim 26 (previously presented): A method according to Claim 1, wherein the plating base film comprises an adhesive layer.

Claim 27 (new): A method according to Claim 1, wherein the plating base film comprises a diffusion preventive layer.

Claim 28 (new): A method according to Claim 7, wherein the plating base film comprises a diffusion preventive layer.